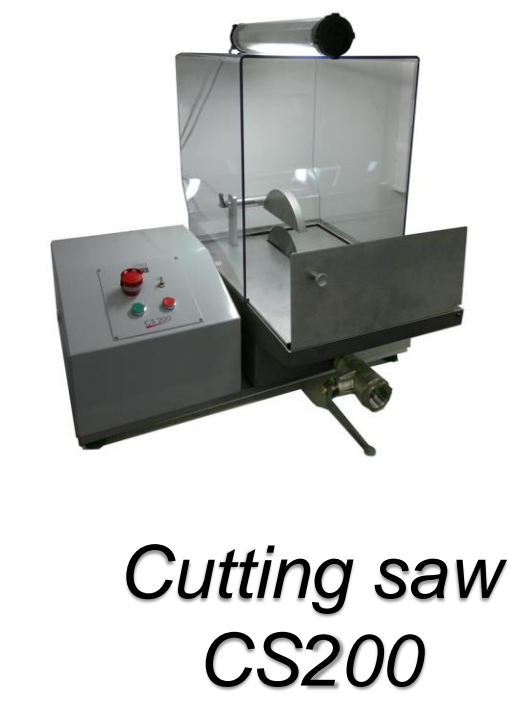
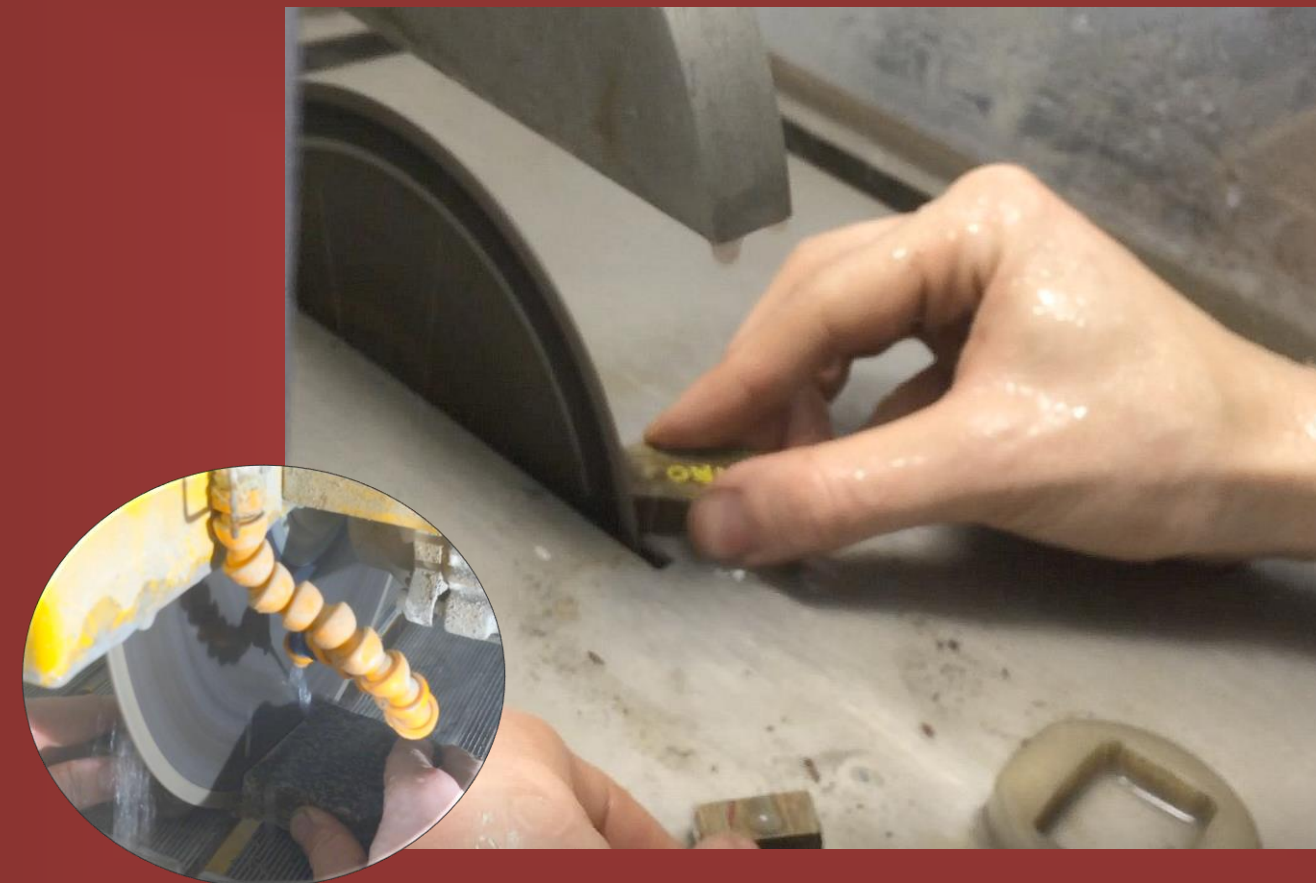


Thin section preparation

Vinci's solution

Sectioning and trimming



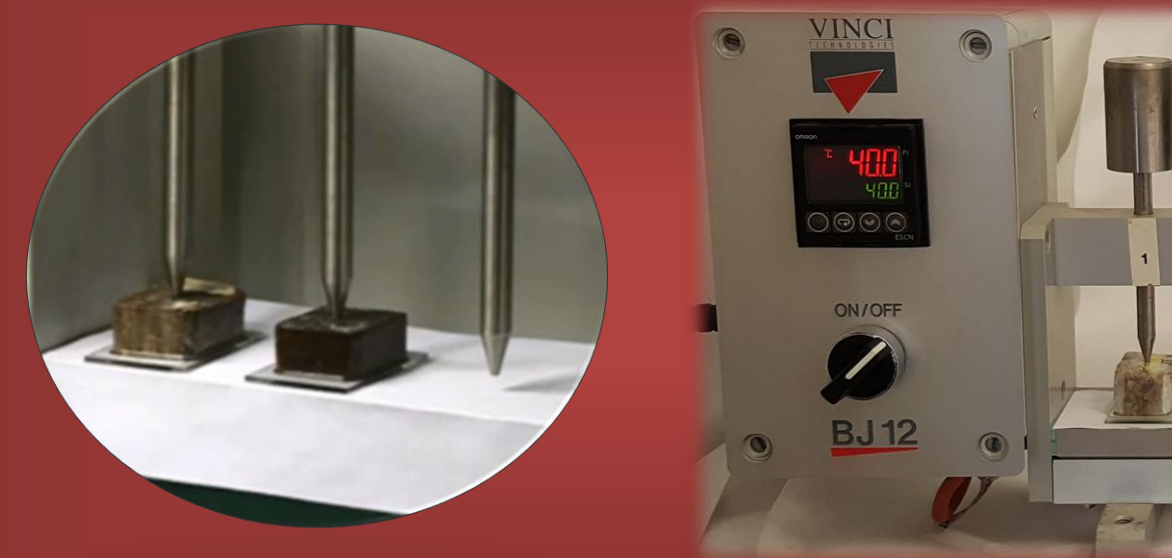
Resin impregnation



Initial face grinding /lapping



Bonding



Thinning the specimen down to 100-500μ thickness



Grinding and lapping down to 30μ thickness



Polishing

